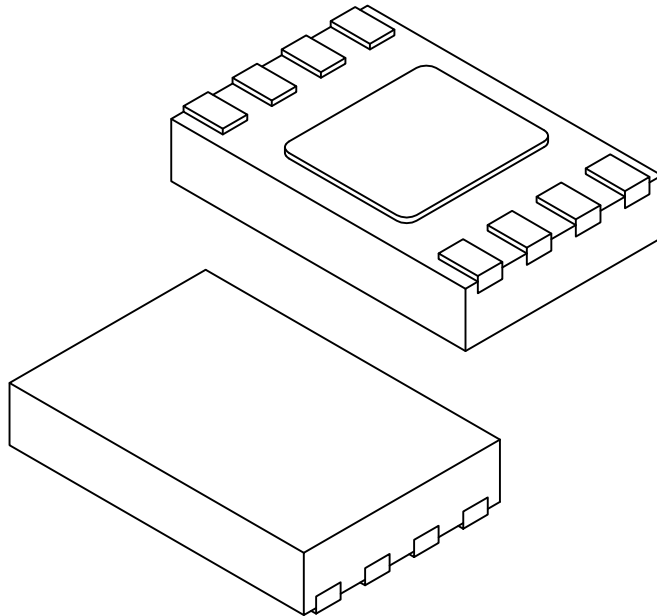


# 8-Lead Ultra Thin Plastic Dual Flat, No Lead Package (Q4B) - 2x3 mm Body [UDFN] Atmel Legacy YNZ Package

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		8		
Pitch	e		0.50 BSC		
Overall Height	A	0.50	0.55	0.60	
Standoff	A1	0.00	0.02	0.05	
Terminal Thickness	A3	0.152 REF			
Overall Length	D	2.00 BSC			
Exposed Pad Length	D2	1.40	1.50	1.60	
Overall Width	E	3.00 BSC			
Exposed Pad Width	E2	1.20	1.30	1.40	
Terminal Width	b	0.18	0.25	0.30	
Terminal Length	L	0.35	0.40	0.45	
Terminal-to-Exposed-Pad	K	0.20	-	-	

**Notes:**

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.